

EV GROUP BRINGS HIGH-SPEED HIGH-PRECISION METROLOGY TO 3D HETEROGENEOUS INTEGRATION – November 17, 2021

EVG today unveiled the EVG®40 NT2 automated metrology system, which provides overlay and critical dimension (CD) measurements for wafer-to-wafer (W2W), die-to-wafer (D2W) and die-to-die (D2D) bonding as well as maskless lithography applications. Designed for high-volume production with feedback loops for real-time process correction and optimization, the EVG40 NT2 helps device manufacturers, foundries and packaging houses accelerate the introduction of new 3D/heterogeneous integration products as well as improve yields and avoid scrapping of highly valuable wafers.



